



Product Change Notification / LIAL-04DLC0554

Date:

11-Aug-2022

Product Category:

Microprocessors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4830 Final Notice: Qualification of ATK as an additional assembly site for selected ATSAMA5D26 and ATSAMA5D27 device families available in 289L LFBGA (14x14x1.4mm) package.

Affected CPNs:

[LIAL-04DLC0554_Affected_CPN_08112022.pdf](#)
[LIAL-04DLC0554_Affected_CPN_08112022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of ATK as an additional assembly site for selected ATSAMA5D26 and ATSAMA5D27 device families available in 289L LFBGA (14x14x1.4mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change

Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	Amkor Technology Korea (K4), INC (ATK)
Wire material	CuPdAu	CuPdAu	CuPdAu
Die attach material	2100AS	2100AS	EP 2300
Molding compound material	KE-G1250LKDS	KE-G1250LKDS	G770FE
Substrate SM material	AUS308	AUS308	AUS308
Substrate Core material	CCL-HL832NX(A-HS)	CCL-HL832NX(A-HS)	HL832NXAHS

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change: To improve on-time delivery performance by qualifying ATK as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date:August 30, 2022 (date code: 2236)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

October 07, 2021: Issued initial notification.

August 11, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on August 30, 2022. Revised the post change die attach material for ATK.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_LIAL-04DLC0554 Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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